

SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520YC09 Yellow

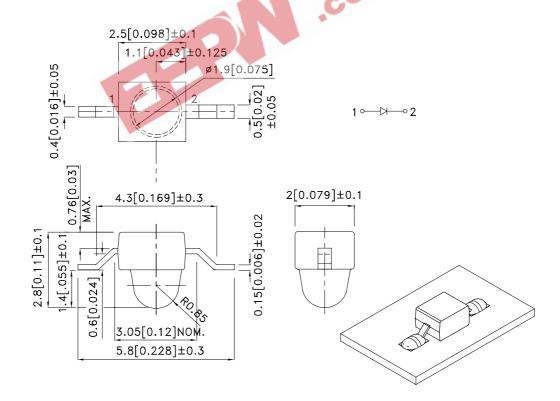
Features

- SUBMINIA TURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- PACKAGE: 1000PCS/REEL.
- RoHS COMPLIANT.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAD1287 **REV NO: V.4 DATE: MAY/08/2007** PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.L.LI ERP: 1202000759

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM2520YC09	Yellow (GaAsP/GaP)	WATER CLEAR	10	30	20°

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590	. 4	nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588	30	nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
С	Capacitance	Yellow	20	40.	pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA
lr	Reverse Current	Yellow		10	uA	V _R =5V

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

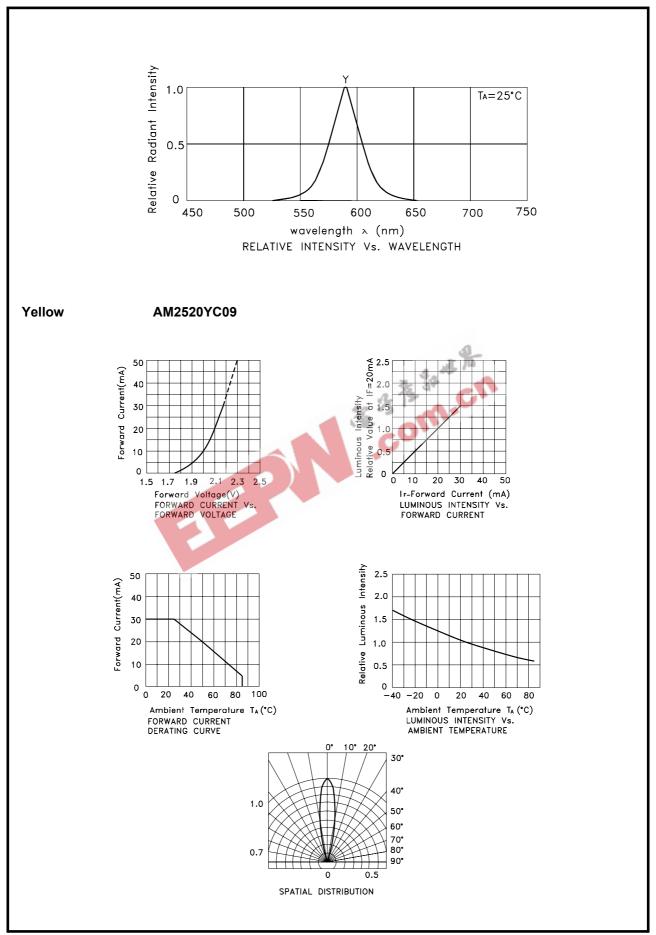
Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: DSAD1287 **REV NO: V.4 DATE: MAY/08/2007** PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.L.LI ERP: 1202000759

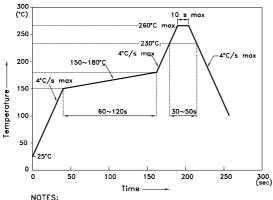


 SPEC NO: DSAD1287
 REV NO: V.4
 DATE: MAY/08/2007
 PAGE: 3 OF 5

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Reflow Soldering Profile For Lead-free SMT Process.

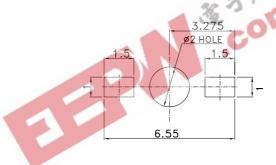


NOTES:

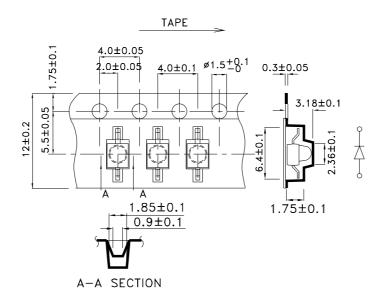
1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm; Tolerance: ± 0.1)



Tape Specifications (Units: mm)

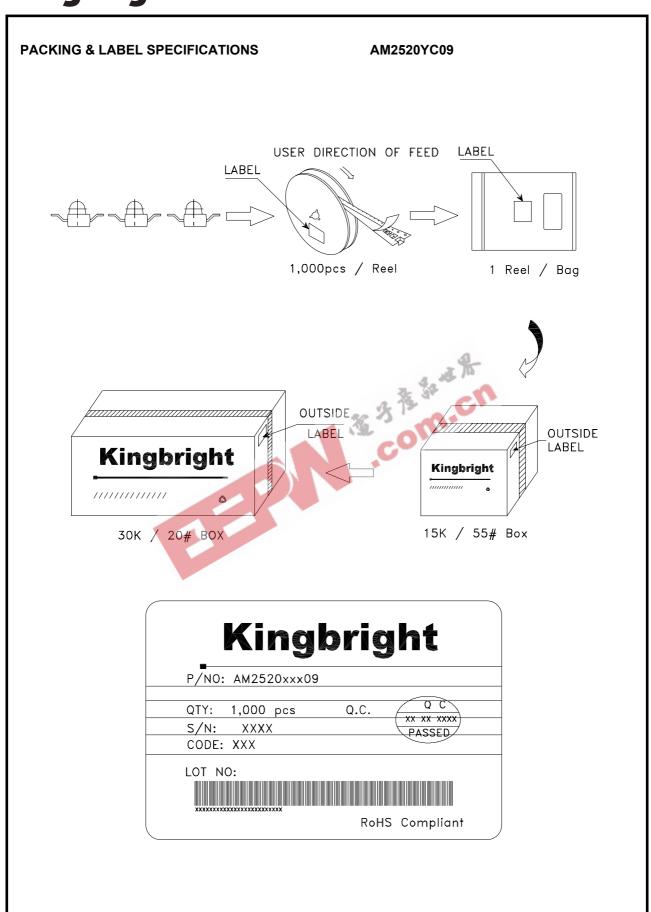


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PAGE: 4 OF 5

ERP: 1202000759



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